



P-Channel Enhancement Mode MOSFET

● **Features**

VDS	VGS	RDSon TYP	ID
-20V	±12V	70mR@-4V5	-5A
		85mR@-2V5	

● **General Description**

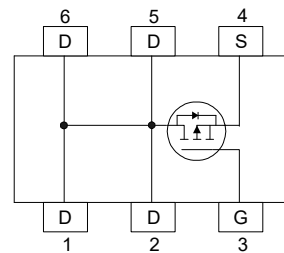
This device is particularly suited for low voltage application such as portable equipment, power management and other battery powered circuits, and low in-line power dissipation are needed in a very small outline surface mount package Excellent thermal and electrical capabilities.

● **Applications**

- Load Switch
- Portable Devices
- DCDC conversion

● **Pin Configuration**

Top View



● **Package Information**

SOT23-6L: mm			
Dim	Min	Max	Typ
A	0.35	0.50	0.38
B	1.50	1.70	1.60
C	2.70	3.00	2.80
D	-	-	0.95
F	-	-	-
H	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
M	0.10	0.20	0.15
α	0°	8°	-



● **Absolute Maximum Ratings** @ $T_A=25^{\circ}\text{C}$ unless otherwise noted

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V_{DSS}	-20	V
Gate-Source Voltage		V_{GSS}	± 12	V
Drain Current (Note 1)	Continuous $T_A=25^{\circ}\text{C}$	I_D	-5	A
	Pulsed (Note 2)		-20	A
Total Power Dissipation (Note 1)		P_D	1500	mW
Operating and Storage Junction Temperature Range		T_J, T_{STG}	-55 to +150	$^{\circ}\text{C}$

Note:

The value of P_D is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^{\circ}\text{C}$. The current rating is based on the DC thermal resistance rating.

1. Minimum footprint
2. Maximum footprint.

● **Electrical Characteristics** @ $T_A = 25^{\circ}\text{C}$ unless otherwise noted, no self-heating.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D=-250\mu\text{A}$	-20	--	--	V
Drain Cut-off Current	I_{DSS}	$V_{DS} = -20V, V_{GS} = 0V$	--	--	-1	μA
Gate-Source Leakage Current	I_{GSS}	$V_{GS} = \pm 12V, V_{DS} = 0V$	--	--	± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$I_D = -250\mu\text{A}, V_{DS} = V_{GS}$	-0.45	-0.75	-1.5	V
Drain-Source On-state Resistance	$R_{DS(on)}$	$V_{GS} = -4.5V, I_D = -3A$	--	70	82	mR
		$V_{GS} = -2.5V, I_D = -2A$	--	85	100	mR
Forward Transconductance	g_{FS}	$V_{DS} = -5V, I_D = -2.8A$	--	6.5	--	S
Input Capacitance	C_{iss}	$V_{DS} = -6V, V_{GS} = 0V$ $f = 1\text{MHz}$	--	415	--	pF
Output Capacitance	C_{oss}		--	223	--	pF
Feedback Capacitance	C_{riss}		--	87	--	pF
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = -6V, R_L = 6R, I_D = -1.0A,$	--	13	25	ns
Turn-off Delay Time	$t_{d(off)}$	$V_{GEN} = -4.5V, R_G = 6R$	--	42	70	ns
Drain-Source Diode Forward Voltage	V_{SD}	$I_S = -1.6A, V_{GS} = 0V$	-0.5	--	-1.2	V



● Typical Performance Characteristics

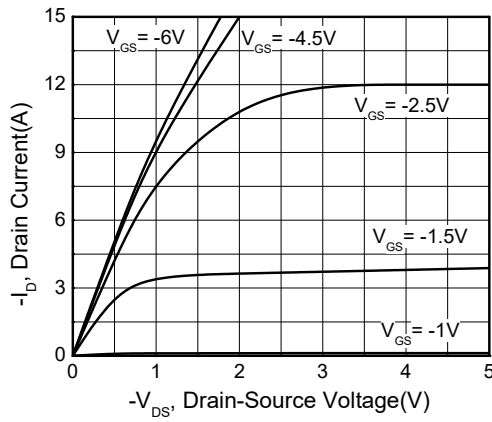


Fig 1. Output Characteristics

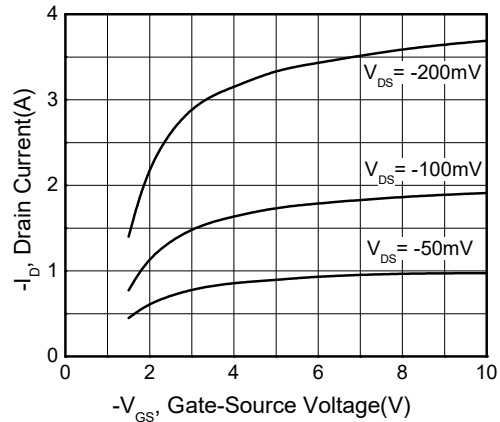


Fig 2. Transfer Characteristics

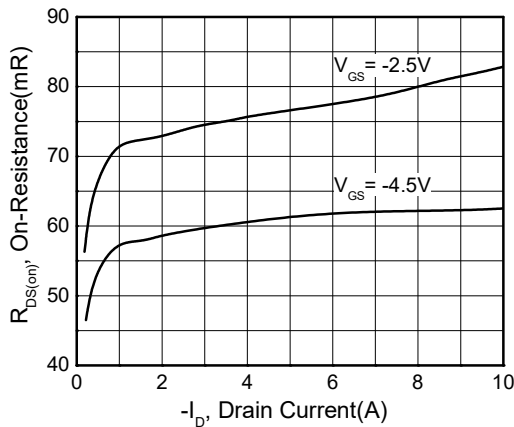


Fig 3. On-Resistance vs. Drain Current

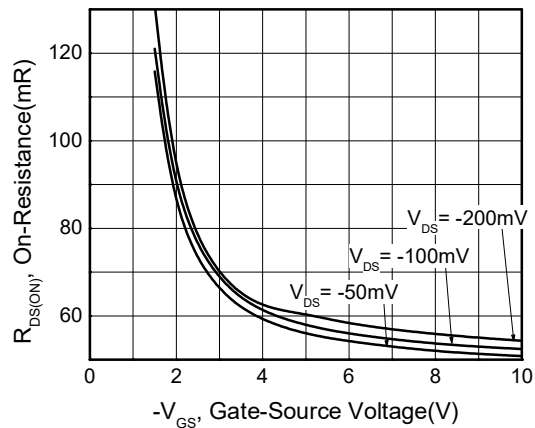


Fig 4. On-Resistance vs. Gate-Source Voltage

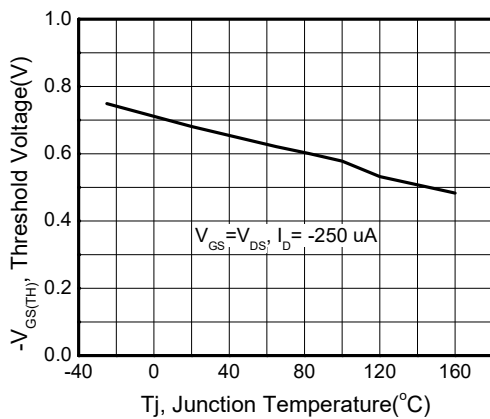


Fig 5. Threshold Voltage

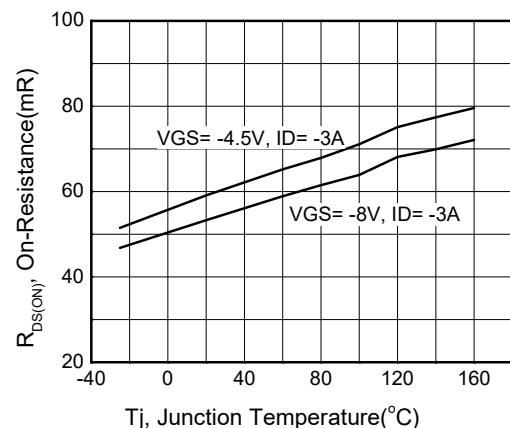


Fig 6. On-Resistance Temperature Coefficient

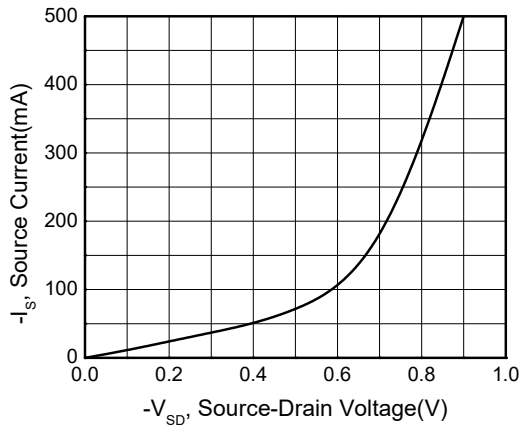


Fig 7. Body Diode Forward Characteristics

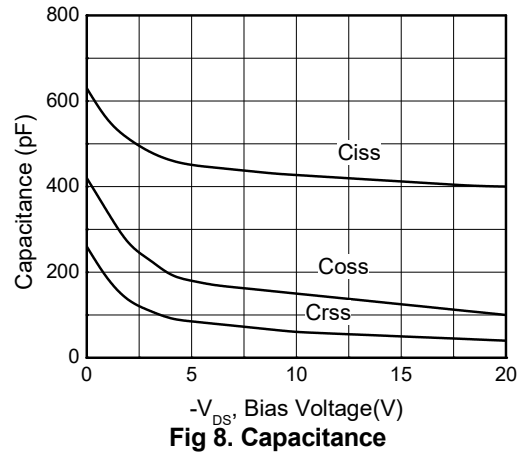


Fig 8. Capacitance

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